

N-Channel 180 V (D-S) MOSFET

PRODUCT SUMMARY		
V_{DS} (V)	$R_{DS(on)}$ (Ω)	I_D (A)
180	0.042 at $V_{GS} = 10$ V	35

FEATURES

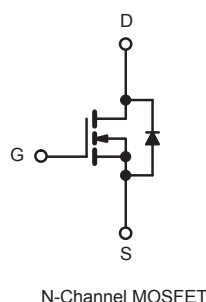
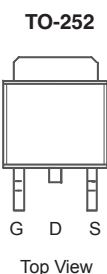
- TrenchFET II Power MOSFET
- 100 % R_g and IS Tested



RoHS
COMPLIANT

APPLICATIONS

- Primary Side Switch



ABSOLUTE MAXIMUM RATINGS ($T_A = 25$ °C, unless otherwise noted)			
Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V_{DS}	180	V
Gate-Source Voltage	V_{GS}	± 20	
Continuous Drain Current ($T_J = 175$ °C) ^b	I_D	$T_C = 25$ °C	35
		$T_C = 125$ °C	19
Pulsed Drain Current	I_{DM}	140	A
Continuous Source Current (Diode Conduction)	I_S	30	
Avalanche Current	I_{AS}	30	
Single Pulse Avalanche Energy	E_{AS}	24	mJ
Maximum Power Dissipation	P_D	$T_C = 25$ °C	85 ^b
		$T_A = 25$ °C	6 ^a
Operating Junction and Storage Temperature Range	T_J, T_{stg}	- 55 to 175	°C

THERMAL RESISTANCE RATINGS					
Parameter	Symbol	Typical	Maximum	Unit	
Junction-to-Ambient ^a	R_{thJA}	$t \leq 10$ s	13	18	°C/W
		Steady State	27	50	
Junction-to-Case (Drain)	R_{thJC}	0.85	1.1		

Notes:

a. Surface mounted on 1" x 1" FR4 board.

b. See SOA curve for voltage derating.

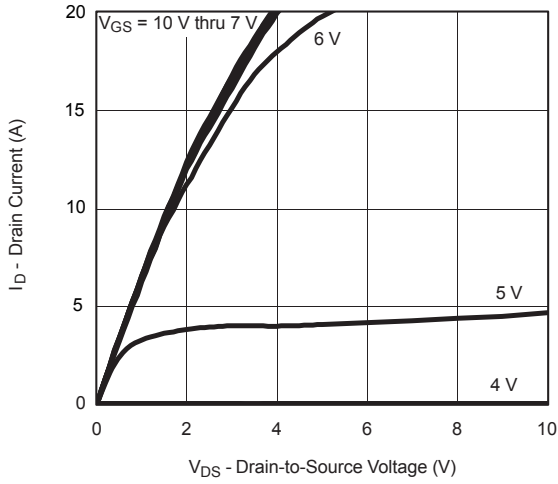
SPECIFICATIONS ($T_J = 25\text{ }^\circ\text{C}$, unless otherwise noted)						
Parameter	Symbol	Test Conditions	Min.	Typ. ^a	Max.	Unit
Static						
Drain-Source Breakdown Voltage	V_{DS}	$V_{GS} = 0\text{ V}, I_D = 250\text{ }\mu\text{A}$	180			V
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\text{ }\mu\text{A}$	2		4	
Gate-Body Leakage	I_{GSS}	$V_{DS} = 0\text{ V}, V_{GS} = \pm 20\text{ V}$			± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 145\text{ V}, V_{GS} = 0\text{ V}$			1	μA
		$V_{DS} = 145\text{ V}, V_{GS} = 0\text{ V}, T_J = 125\text{ }^\circ\text{C}$			50	
		$V_{DS} = 145\text{ V}, V_{GS} = 0\text{ V}, T_J = 175\text{ }^\circ\text{C}$			250	
On-State Drain Current ^b	$I_{D(on)}$	$V_{DS} \geq 5\text{ V}, V_{GS} = 10\text{ V}$	35			A
Drain-Source On-State Resistance ^b	$R_{DS(on)}$	$V_{GS} = 10\text{ V}, I_D = 10\text{ A}$		0.042	0.046	Ω
Forward Transconductance ^b	g_{fs}	$V_{DS} = 145\text{ V}, I_D = 10\text{ A}$		16		S
Dynamic^a						
Input Capacitance	C_{iss}	$V_{GS} = 0\text{ V}, V_{DS} = 145\text{ V}, F = 1\text{ MHz}$		6750		μF
Output Capacitance	C_{oss}			1250		
Reverse Transfer Capacitance	C_{rss}			180		
Total Gate Charge ^c	Q_g	$V_{DS} = 145\text{ V}, V_{GS} = 10\text{ V}, I_D = 10\text{ A}$		15		nC
Gate-Source Charge ^c	Q_{gs}			8		
Gate-Drain Charge ^c	Q_{gd}			12		
Gate Resistance	R_g		1.2		2.9	Ω
Turn-On Delay Time ^c	$t_{d(on)}$	$V_{DD} = 145\text{ V}, R_L = 5.2\text{ }\Omega$ $I_D \cong 10\text{ A}, V_{GEN} = 10\text{ V}, R_g = 2.5\text{ }\Omega$		11	27	ns
Rise Time ^c	t_r			34	76	
Turn-Off Delay Time ^c	$t_{d(off)}$			22	48	
Fall Time ^c	t_f			45	90	
Source-Drain Diode Ratings and Characteristics ($T_C = 25\text{ }^\circ\text{C}$)						
Continuous Source-Drain Diode Current	I_S	$T_C = 25\text{ }^\circ\text{C}$			30	A
Pulsed Current	I_{SM}				140	
Diode Forward Voltage ^b	V_{SD}	$I_F = 19\text{ A}, V_{GS} = 0\text{ V}$		0.7	1.5	V
Source-Drain Reverse Recovery Time	t_{rr}	$I_F = 19\text{ A}, di/dt = 100\text{ A}/\mu\text{s}$		160	250	ns

Notes:

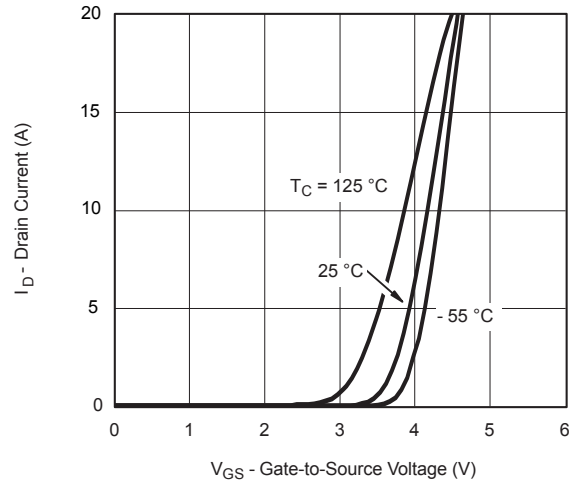
- Guaranteed by design, not subject to production testing.
- Pulse test; pulse width $\leq 300\text{ }\mu\text{s}$, duty cycle $\leq 2\%$.
- Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

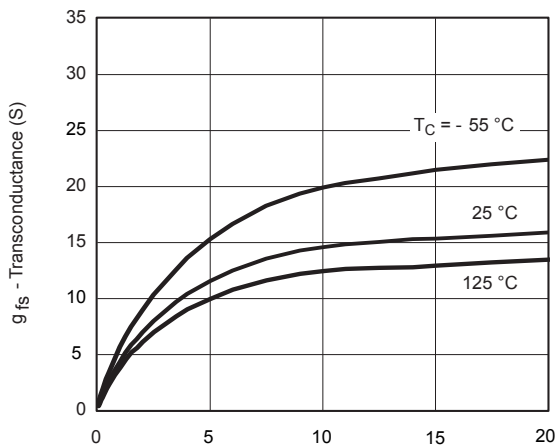
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



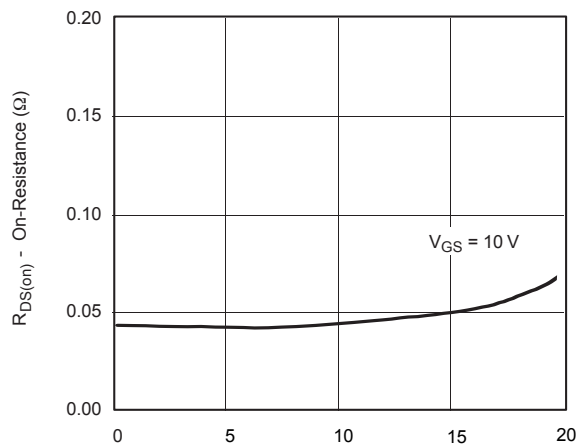
Output Characteristics



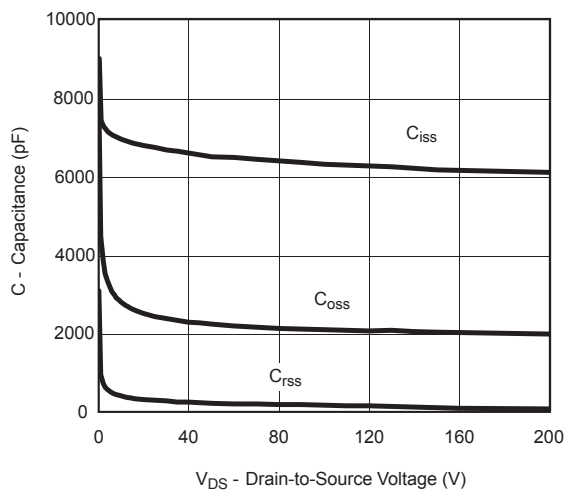
Transfer Characteristics



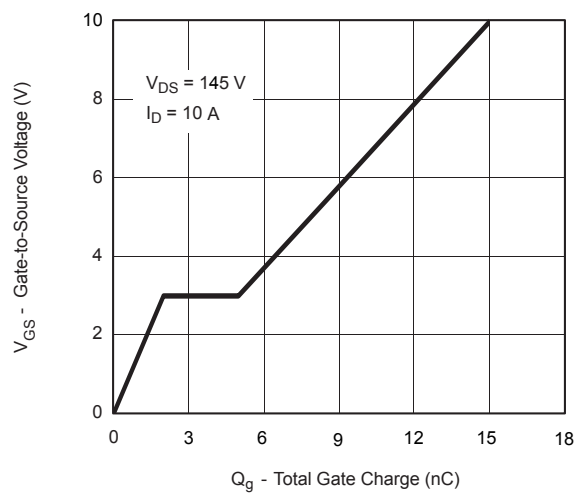
Transconductance



On-Resistance vs. Drain Current

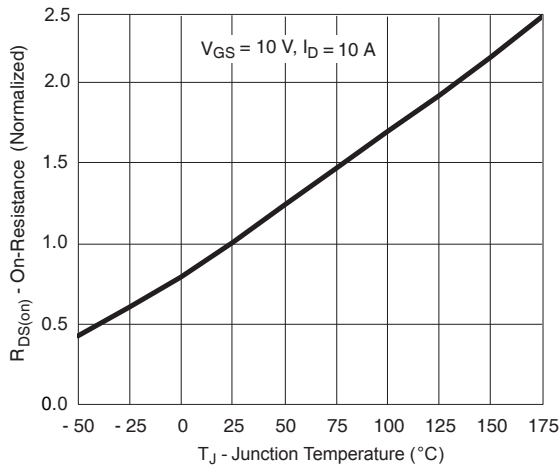


Capacitance

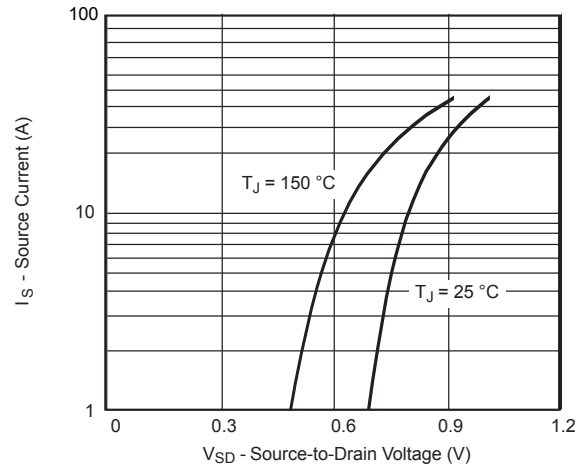


Gate Charge

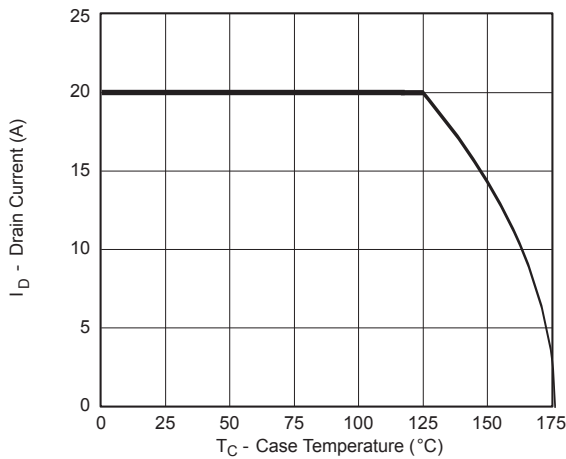
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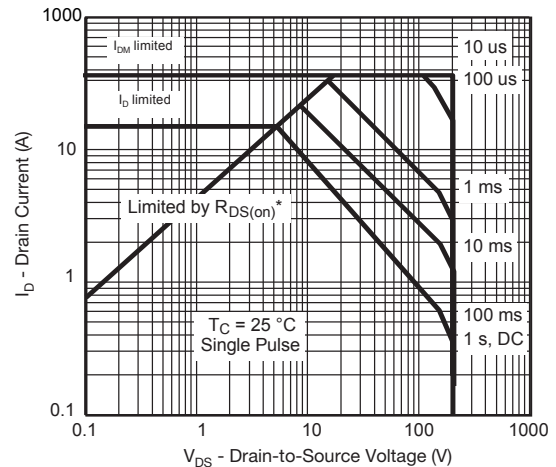
On-Resistance vs. Junction Temperature



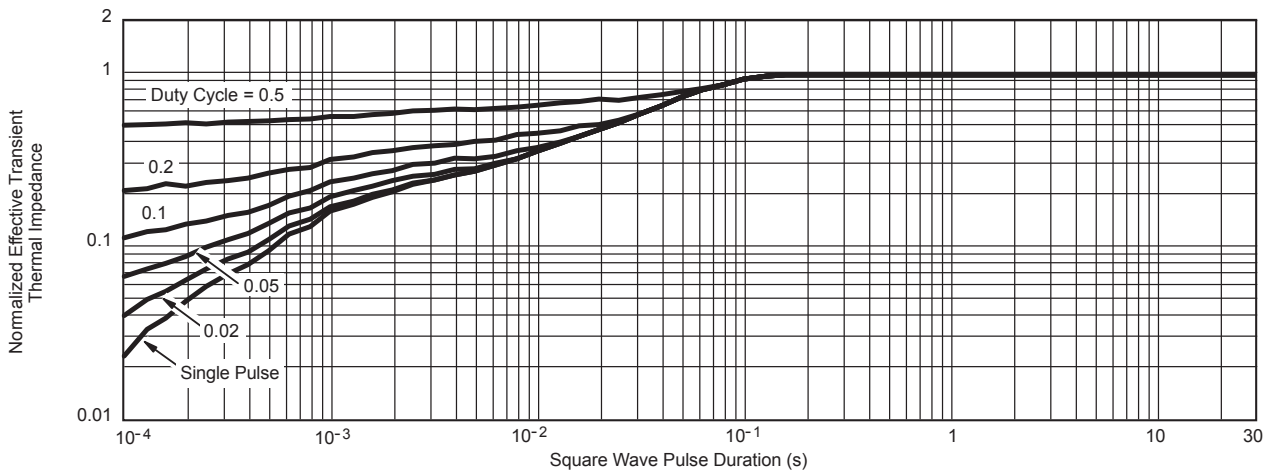
Source-Drain Diode Forward Voltage



Maximum Avalanche Drain Current vs. Case Temperature

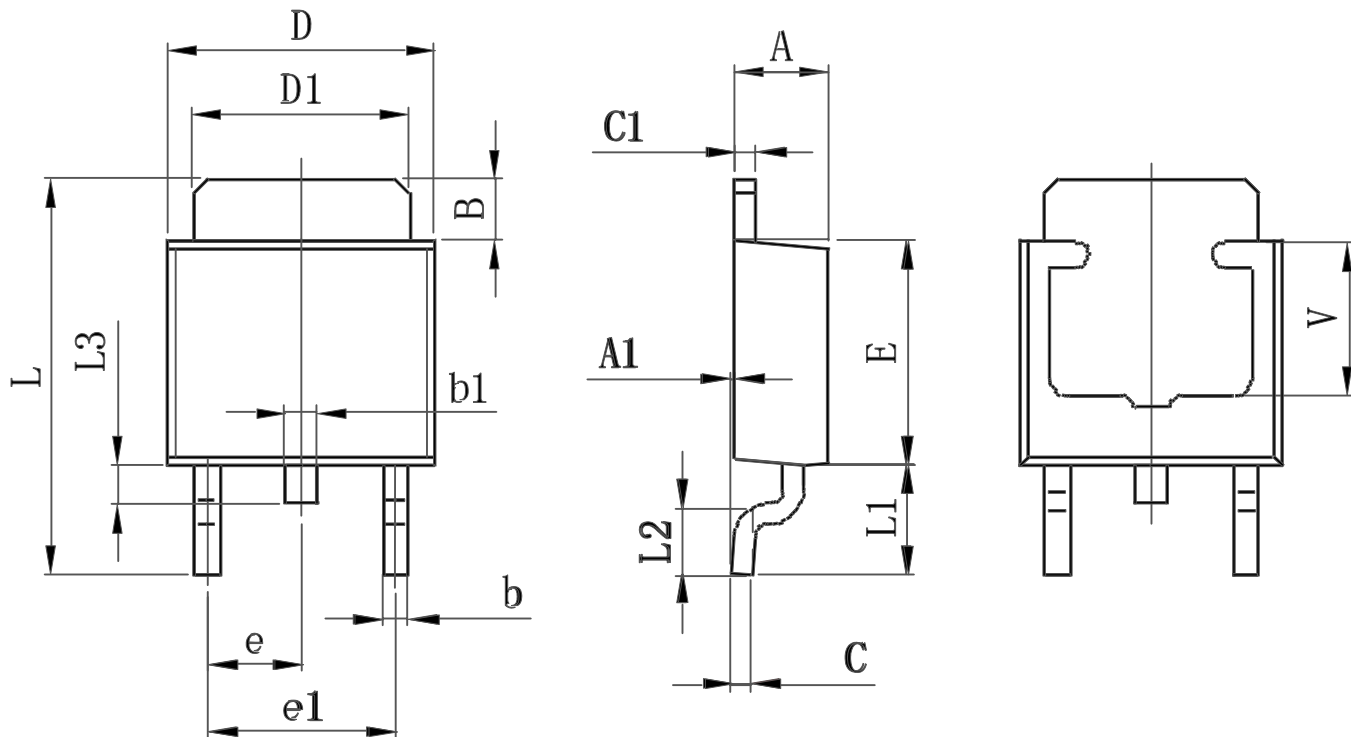


Safe Operating Area
* $V_{GS} >$ minimum V_{GS} at which $R_{DS(on)}$ is specified



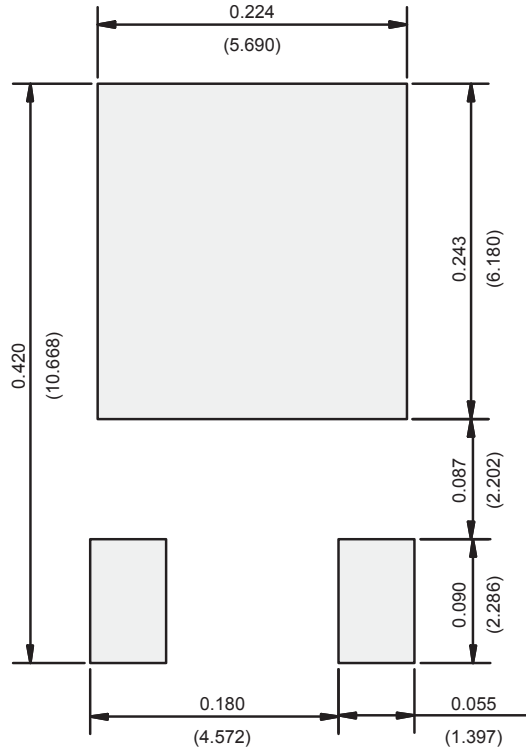
Normalized Thermal Transient Impedance, Junction-to-Case

TO-252-2L PACKAGE OUTLINE DIMENSIONS



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	2.200	2.400	0.087	0.094
A1	0.000	0.127	0.000	0.005
B	1.350	1.650	0.053	0.065
b	0.500	0.700	0.020	0.028
b1	0.700	0.900	0.028	0.035
c	0.430	0.580	0.017	0.023
c1	0.430	0.580	0.017	0.023
D	6.350	6.650	0.250	0.262
D1	5.200	5.400	0.205	0.213
E	5.400	5.700	0.213	0.224
e	2.300 TYP.		0.091 TYP.	
e1	4.500	4.700	0.177	0.185
L	9.500	9.900	0.374	0.390
L1	2.550	2.900	0.100	0.114
L2	1.400	1.780	0.055	0.070
L3	0.600	0.900	0.024	0.035
V	3.800 REF.		0.150 REF.	

RECOMMENDED MINIMUM PADS FOR DPAK (TO-252)



Recommended Minimum Pads
Dimensions in Inches/(mm)

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